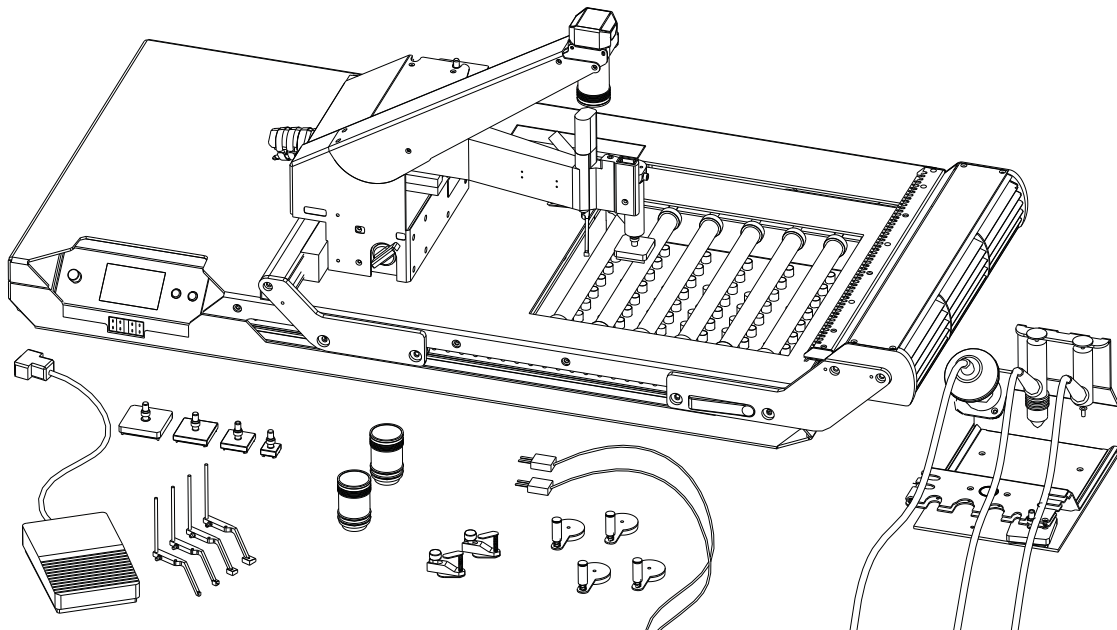


**Rework Technic – EXPERT 10.6-HV**


Rework Station with 3000W Hybrid Underheater for PCBs up to 245x275mm<sup>2</sup>. Heating area is analogues to PCB size adjustable. Automated SMD placement process by Auto Vision Placer (AVP) incl. Easy Solder software package and DBL 06 control unit with six high resolution sensors inputs for thermocouples (Type K).

This system is particularly suitable for mid size and big PCBs with Fine Pitch components with varying package dimensions.

**Standard Equipment (Art.No. DB00.1065)**

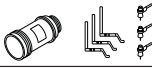


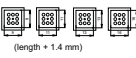

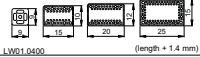


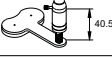

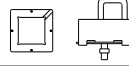



- Tool set for dispensing, placing, residual solder removal and soldering with magazine
- Set of placement nozzles (BGA/CSP) 3mm, 5mm, 8mm, 10mm
- Set of solder nozzles (BGA) 15mm, 27mm, 35mm, 40mm
- Two camera lenses (BGA und CSP)
- Two thermo couple sensors (type K)
- Four PCB magnet holder 40,5mm (standard)
- Two PCB clips to install at hand rest
- Foot switch
- Rework ABC and manual

**Technical Data**

System power consumption:	3500 VA	
Power solder pen :	300 W, 35 l/min	
Power underheater:	600 - 3000 W, 6 x IR lamps	
Effective heating area:	245 x 275 mm <sup>2</sup>	
Max. PCB size:	390 x 500 mm <sup>2</sup>	
Resolution motion system:	0,001 mm	
Placement accuracy :	± 0,015 mm	(Flip Chip)*
	± 0,030 mm	(CSP)
	± 0,040 mm	(BGA)
	± 0,070 mm	(Maxi BGA)*
High resolution CMOS-camera:	5 Mio. Pixel, USB2	
Camera field of view (FOV):	14 x 18 mm <sup>2</sup>	(Flip Chip)*
	28 x 37 mm <sup>2</sup>	(CSP)
	37 x 50 mm <sup>2</sup>	(BGA)
	65 x 85 mm <sup>2</sup>	(Maxi BGA)*
Mains:	1 Phase, 230VAC, 25A/Phase, Fuse 16A	
	Connector Type CEE 32A (3 phase)	
Pressurized air:	5 - 8 bar, 100l/min	
	clean dry air	
Foot print:	460 x 865 mm <sup>2</sup>	
*Optional Extras		

## Rework Technic – EXPERT 10.6-HV

### Optional Extras

SF66.0004	Micro SMD nozzles and lens for AVP 4 licence MS, 3 n, 3 solder n, lens FC		SF66.0004	1 piece
DVSX.0007	Report with pcb identification for ES 05, licence RP	 Report	DVSX.0007	1 piece
SF66.0110	Lens Maxi BGA for AVP4/4XL, f=16mm, 65*85mm	 Maxi-BGA AVP4	SF66.0110	1 piece
LW40.1097	Soldering nozzle set CSP/QFN (lead free)* for all CSP types, 4 pieces (9, 11, 13, 16)	 (length = 1.4 mm)	LW40.1097	1 piece
LW40.1099	Solder nozzle set BGA 7 for all (98%) types of BGA, 7 pieces		LW40.1099	1 piece
LW01.0400	Soldering tool set SO (lead free)* for all SO...SOL...TSOP, 4 pieces	 (length = 1.4 mm)	LW01.0400	1 piece
LW01.0100	Soldering tool set QFP for all PLCC ...QFP, 7 pieces		LW01.0100	1 piece
SF36.1001	PCB flex support 40.5 for HIF 08 and IRF, "10 pin"		SF36.1001	1 piece
SF03.0014	PCB magnet holder Easy Lock 40.5 (snap) for IR/IRD/IRH/IRF radiation element	 40.5	SF03.0014	1 piece
SF03.0019	PCB clamping holder 40.5 with 3 fingers for mobil phone pcs on HB05/IR/IRD/IRH/IRF	 40.5	SF03.0019	1 piece
LWxx.xxx4	Reballing oven and masks for all types of BGA/CSP, your choice		LWxx.xxx4	1 piece
SF71.0001	Side Camera for ES 05, camera, stand, cable, DVD		SF71.0001	1 piece
DB00.0025	Nitrogen input for DBL 04/05/06 (2.p.r) reduces consumption of N2 for vacuum	 N <sub>2</sub>	DB00.0025	1 piece
SF00.0028	Socket CEE 32 A for HIF 08/09 / IRF 07 with hints		SF00.0028	1 piece